

FIG. 1a

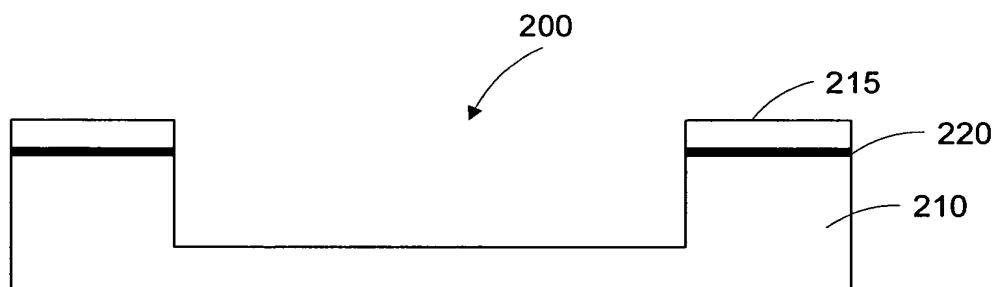


FIG. 1b

Device Packages with Low Stress Assembly Process
P106-US – Tarn
G. Muir 408-737-8100, ext. 136

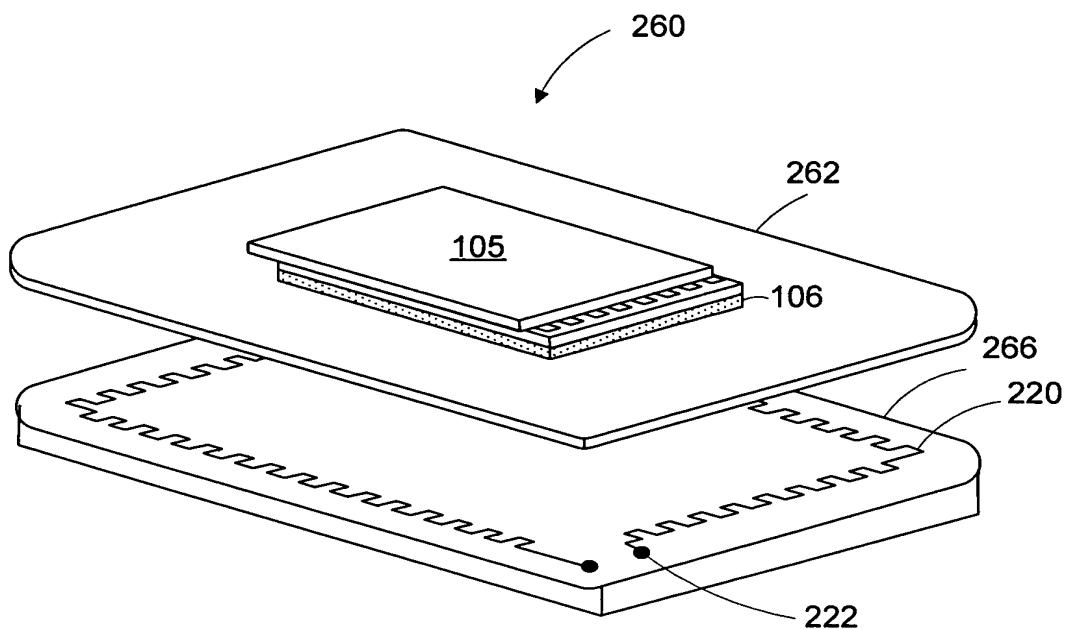


FIG. 2

Device Packages with Low Stress Assembly Process
P106-US – Tarn
G. Muir 408-737-8100, ext. 136

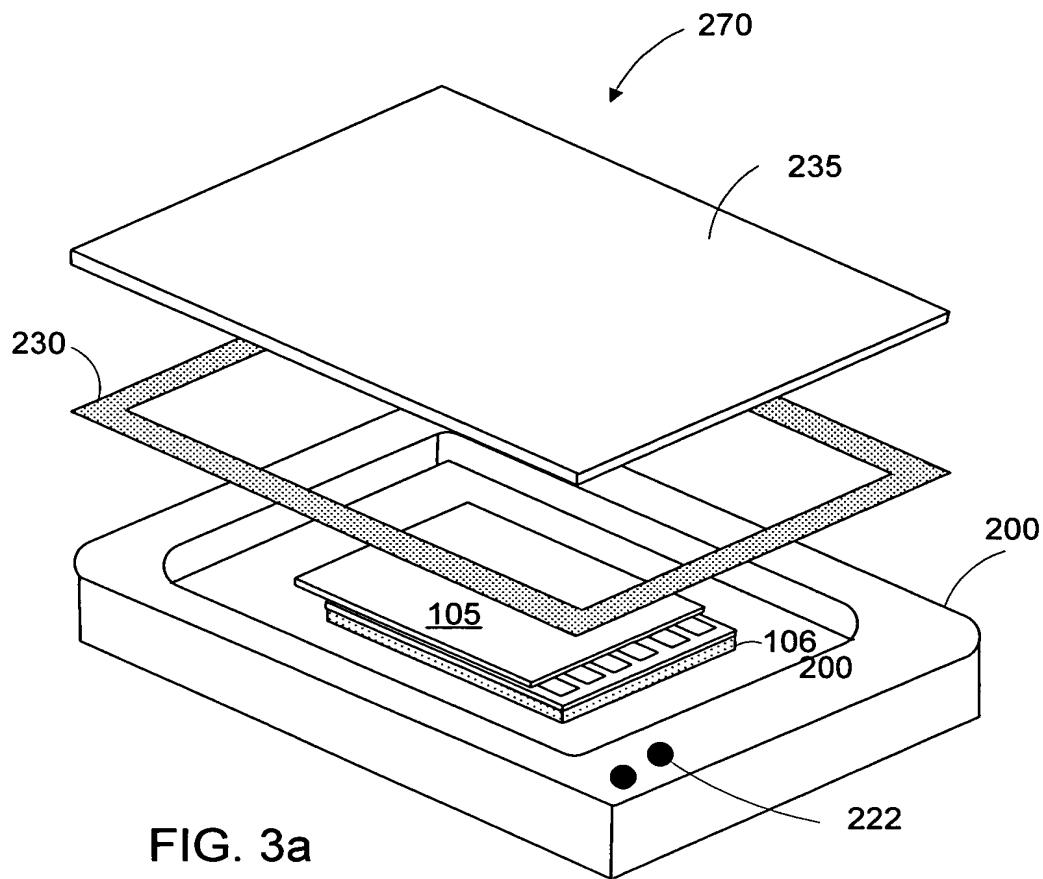


FIG. 3a

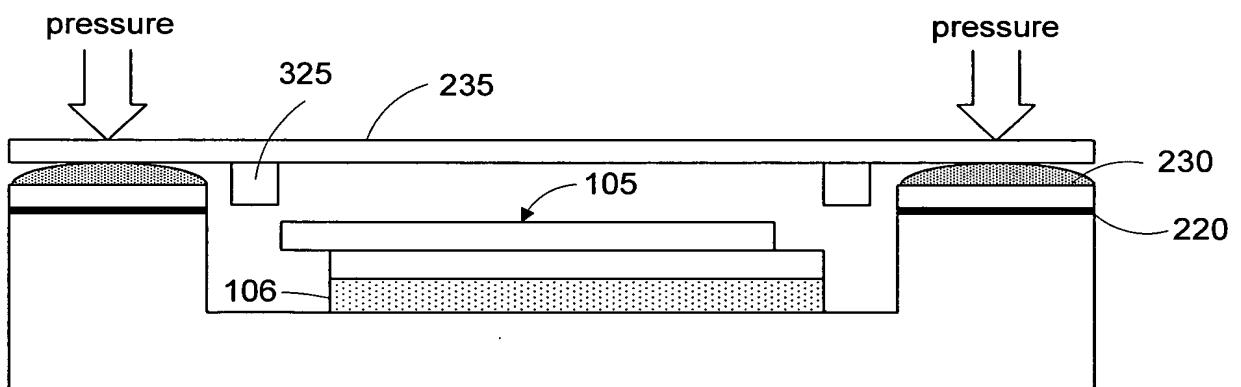


FIG. 3b

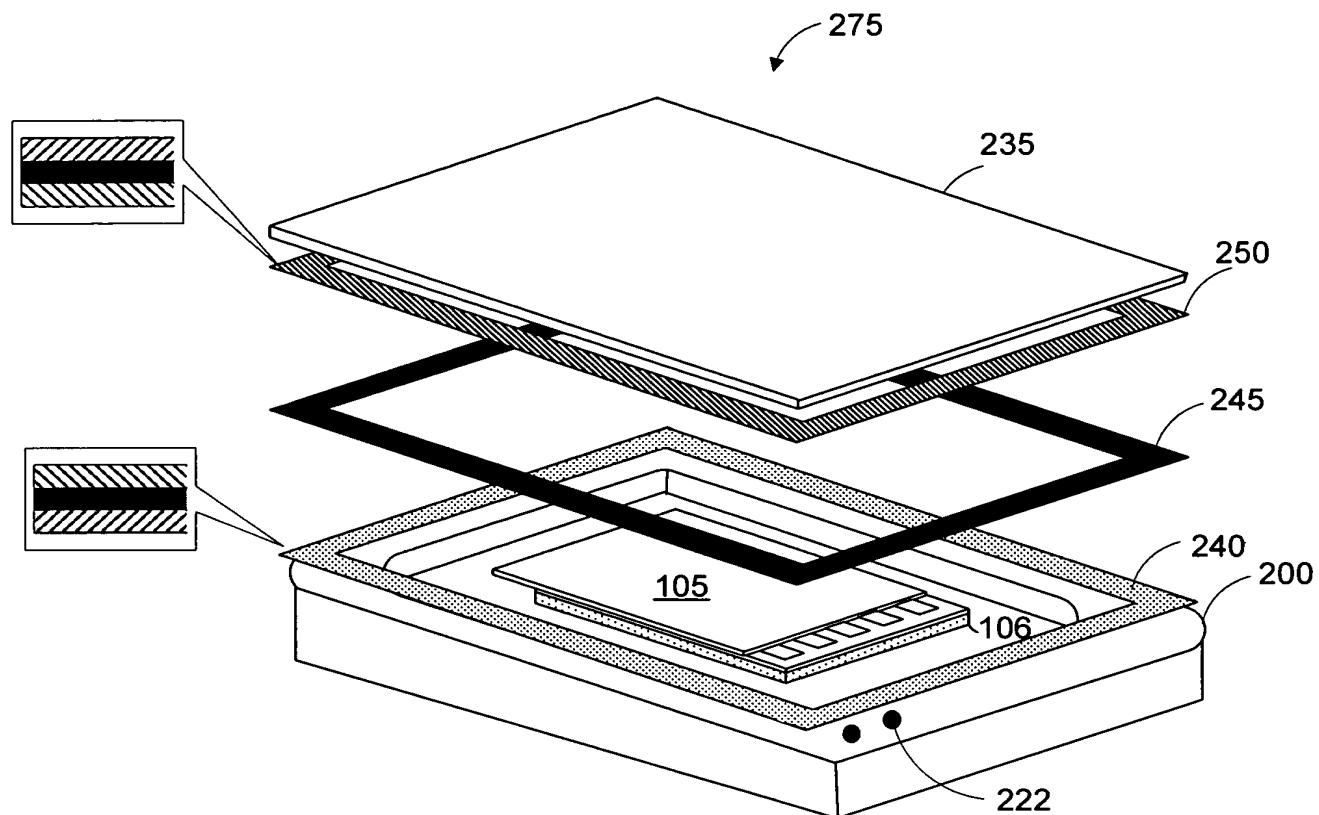


FIG. 4a

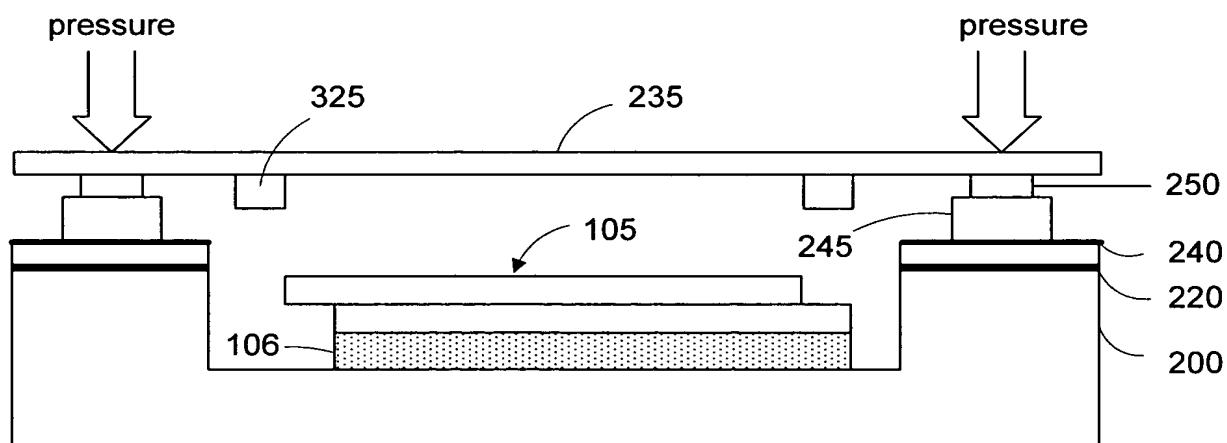


FIG. 4b

Device Packages with Low Stress Assembly Process
P106-US -- Tarn
G. Muir 408-737-8100, ext. 136

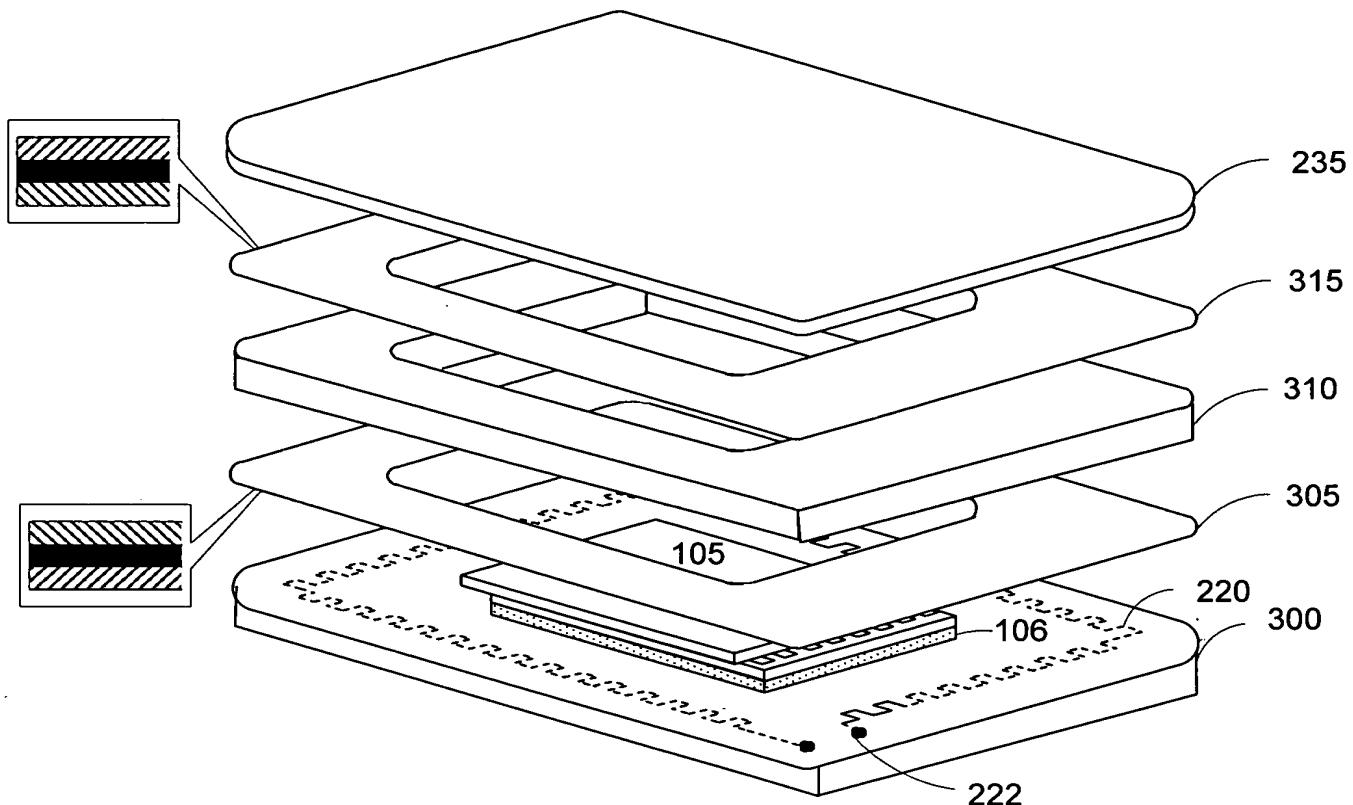


FIG. 5a

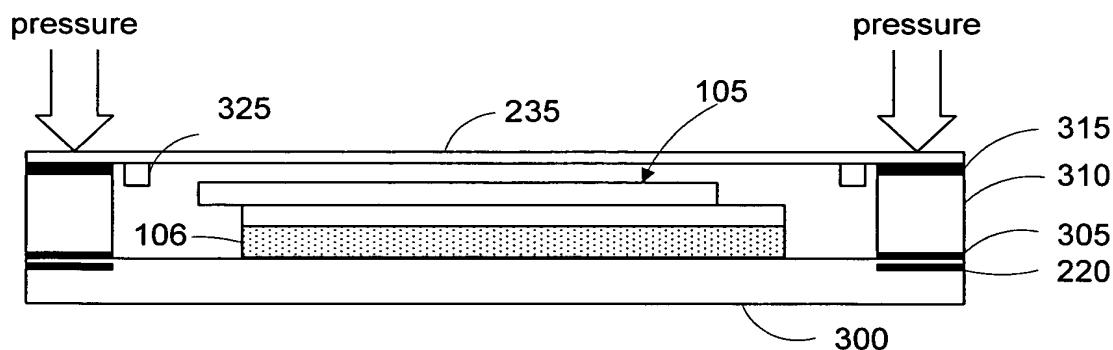


FIG. 5b

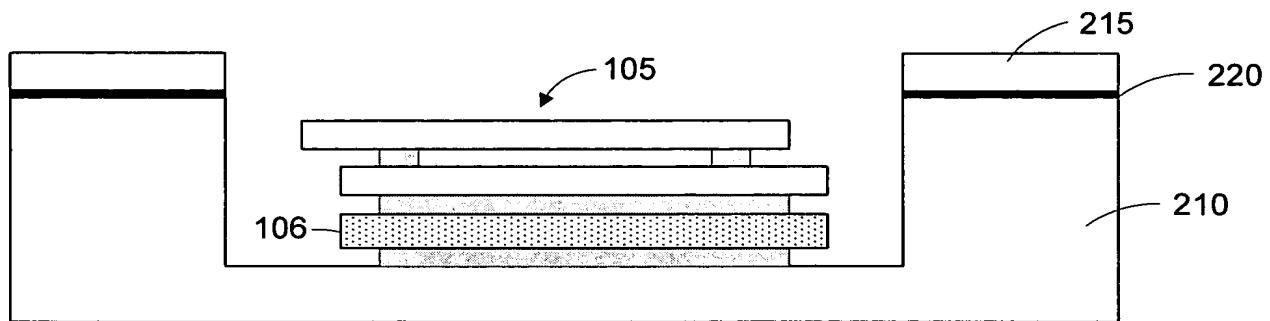


FIG. 6a

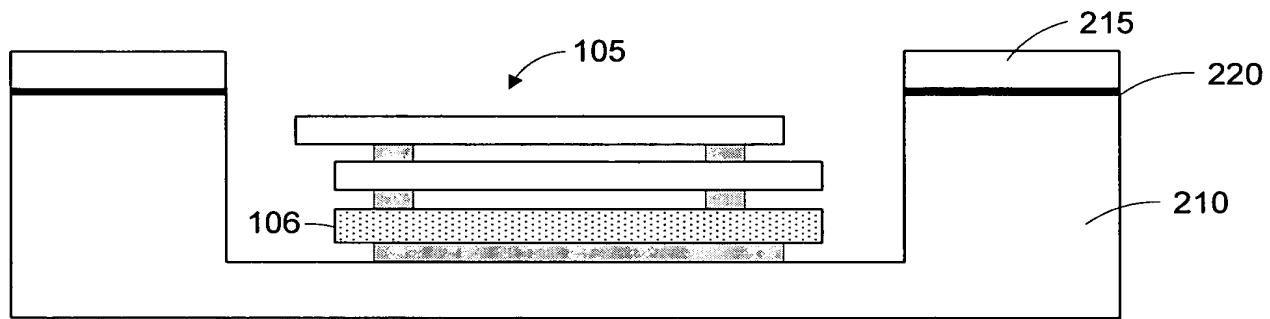


FIG. 6b

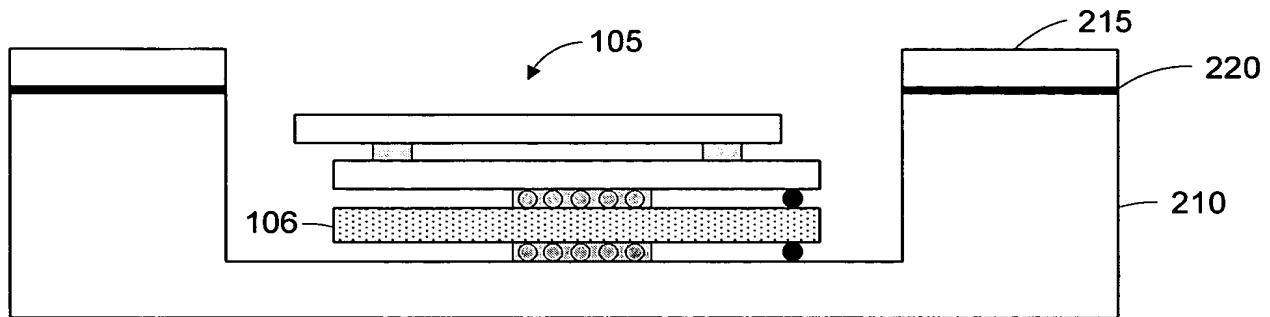


FIG. 6c

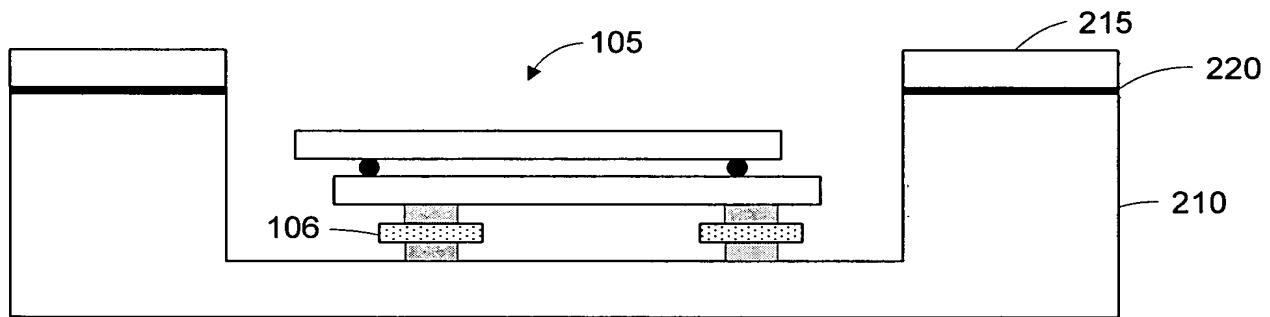


FIG. 6d